

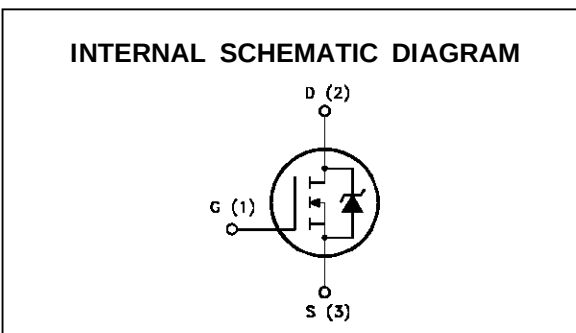
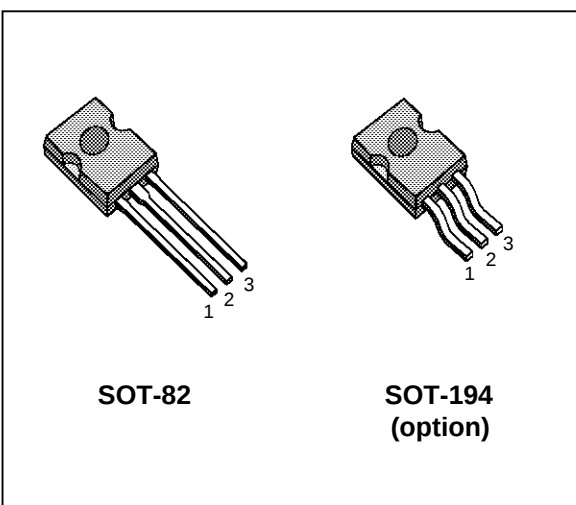
## N - CHANNEL ENHANCEMENT MODE POWER MOS TRANSISTOR

| TYPE     | V <sub>DSS</sub> | R <sub>DS(on)</sub> | I <sub>D</sub> |
|----------|------------------|---------------------|----------------|
| STK22N06 | 60 V             | < 0.065 $\Omega$    | 22 A           |

- TYPICAL R<sub>DS(on)</sub> = 0.048  $\Omega$
- AVALANCHE RUGGED TECHNOLOGY
- 100% AVALANCHE TESTED
- REPETITIVE AVALANCHE DATA AT 100°C
- LOW GATE CHARGE
- HIGH CURRENT CAPABILITY
- 175°C OPERATING TEMPERATURE
- APPLICATION ORIENTED CHARACTERIZATION

### APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SOLENOID AND RELAY DRIVERS
- REGULATORS
- DC-DC & DC-AC CONVERTERS
- MOTOR CONTROL, AUDIO AMPLIFIERS
- AUTOMOTIVE ENVIRONMENT (INJECTION, ABS, AIR-BAG, LAMPDRIVERS, Etc.)



### ABSOLUTE MAXIMUM RATINGS

| Symbol              | Parameter                                              | Value      | Unit |
|---------------------|--------------------------------------------------------|------------|------|
| V <sub>DS</sub>     | Drain-source Voltage (V <sub>GS</sub> = 0)             | 60         | V    |
| V <sub>DGR</sub>    | Drain- gate Voltage (R <sub>GS</sub> = 20 k $\Omega$ ) | 60         | V    |
| V <sub>GS</sub>     | Gate-source Voltage                                    | $\pm 20$   | V    |
| I <sub>D</sub>      | Drain Current (continuous) at T <sub>c</sub> = 25 °C   | 22         | A    |
| I <sub>D</sub>      | Drain Current (continuous) at T <sub>c</sub> = 100 °C  | 15         | A    |
| I <sub>DM</sub> (•) | Drain Current (pulsed)                                 | 88         | A    |
| P <sub>tot</sub>    | Total Dissipation at T <sub>c</sub> = 25 °C            | 65         | W    |
|                     | Derating Factor                                        | 0.43       | W/°C |
| T <sub>stg</sub>    | Storage Temperature                                    | -65 to 175 | °C   |
| T <sub>j</sub>      | Max. Operating Junction Temperature                    | 175        | °C   |

(•) Pulse width limited by safe operating area

**THERMAL DATA**

|                |                                                |     |      |               |
|----------------|------------------------------------------------|-----|------|---------------|
| $R_{thj-case}$ | Thermal Resistance Junction-case               | Max | 2.31 | $^{\circ}C/W$ |
| $R_{thj-amb}$  | Thermal Resistance Junction-ambient            | Max | 80   | $^{\circ}C/W$ |
| $R_{thj-amb}$  | Thermal Resistance Case-sink                   | Typ | 0.7  | $^{\circ}C/W$ |
| $T_I$          | Maximum Lead Temperature For Soldering Purpose |     | 275  | $^{\circ}C$   |

**AVALANCHE CHARACTERISTICS**

| Symbol   | Parameter                                                                                                                   | Max Value | Unit |
|----------|-----------------------------------------------------------------------------------------------------------------------------|-----------|------|
| $I_{AR}$ | Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by $T_j$ max, $\delta < 1\%$ )                         | 22        | A    |
| $E_{AS}$ | Single Pulse Avalanche Energy (starting $T_j = 25^{\circ}C$ , $I_D = I_{AR}$ , $V_{DD} = 25 V$ )                            | 100       | mJ   |
| $E_{AR}$ | Repetitive Avalanche Energy (pulse width limited by $T_j$ max, $\delta < 1\%$ )                                             | 25        | mJ   |
| $I_{AR}$ | Avalanche Current, Repetitive or Not-Repetitive ( $T_c = 100^{\circ}C$ , pulse width limited by $T_j$ max, $\delta < 1\%$ ) | 15        | A    |

**ELECTRICAL CHARACTERISTICS** ( $T_{case} = 25^{\circ}C$  unless otherwise specified)

**OFF**

| Symbol        | Parameter                                        | Test Conditions                                                                              | Min. | Typ. | Max.        | Unit               |
|---------------|--------------------------------------------------|----------------------------------------------------------------------------------------------|------|------|-------------|--------------------|
| $V_{(BR)DSS}$ | Drain-source Breakdown Voltage                   | $I_D = 250 \mu A$ $V_{GS} = 0$                                                               | 60   |      |             | V                  |
| $I_{DSS}$     | Zero Gate Voltage Drain Current ( $V_{GS} = 0$ ) | $V_{DS} = \text{Max Rating}$<br>$V_{DS} = \text{Max Rating} \times 0.8$ $T_c = 125^{\circ}C$ |      |      | 250<br>1000 | $\mu A$<br>$\mu A$ |
| $I_{GSS}$     | Gate-body Leakage Current ( $V_{DS} = 0$ )       | $V_{GS} = \pm 20 V$                                                                          |      |      | $\pm 100$   | nA                 |

**ON (\*)**

| Symbol       | Parameter                         | Test Conditions                                                                 | Min. | Typ.  | Max.          | Unit                 |
|--------------|-----------------------------------|---------------------------------------------------------------------------------|------|-------|---------------|----------------------|
| $V_{GS(th)}$ | Gate Threshold Voltage            | $V_{DS} = V_{GS}$ $I_D = 250 \mu A$                                             | 2    | 2.9   | 4             | V                    |
| $R_{DS(on)}$ | Static Drain-source On Resistance | $V_{GS} = 10V$ $I_D = 11 A$<br>$V_{GS} = 10V$ $I_D = 11 A$ $T_c = 100^{\circ}C$ |      | 0.048 | 0.065<br>0.13 | $\Omega$<br>$\Omega$ |
| $I_{D(on)}$  | On State Drain Current            | $V_{DS} > I_{D(on)} \times R_{DS(on)max}$<br>$V_{GS} = 10 V$                    | 22   |       |               | A                    |

**DYNAMIC**

| Symbol                              | Parameter                                                               | Test Conditions                                        | Min. | Typ.             | Max.              | Unit           |
|-------------------------------------|-------------------------------------------------------------------------|--------------------------------------------------------|------|------------------|-------------------|----------------|
| $g_{fs} (*)$                        | Forward Transconductance                                                | $V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $I_D = 11 A$ | 6    | 10               |                   | S              |
| $C_{iss}$<br>$C_{oss}$<br>$C_{rss}$ | Input Capacitance<br>Output Capacitance<br>Reverse Transfer Capacitance | $V_{DS} = 25 V$ $f = 1 MHz$ $V_{GS} = 0$               |      | 700<br>320<br>90 | 900<br>450<br>150 | pF<br>pF<br>pF |

**ELECTRICAL CHARACTERISTICS** (continued)**SWITCHING ON**

| Symbol                        | Parameter                                                    | Test Conditions                                                                                                         | Min. | Typ.         | Max.      | Unit           |
|-------------------------------|--------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------|------|--------------|-----------|----------------|
| $t_{d(on)}$<br>$t_r$          | Turn-on Time<br>Rise Time                                    | $V_{DD} = 30\text{ V}$ $I_D = 3\text{ A}$<br>$R_G = 50\ \Omega$ $V_{GS} = 10\text{ V}$<br>(see test circuit, figure 3)  |      | 30<br>90     | 45<br>130 | ns<br>ns       |
| $(di/dt)_{on}$                | Turn-on Current Slope                                        | $V_{DD} = 40\text{ V}$ $I_D = 22\text{ A}$<br>$R_G = 50\ \Omega$ $V_{GS} = 10\text{ V}$<br>(see test circuit, figure 5) |      | 230          |           | A/ $\mu$ s     |
| $Q_g$<br>$Q_{gs}$<br>$Q_{gd}$ | Total Gate Charge<br>Gate-Source Charge<br>Gate-Drain Charge | $V_{DD} = 40\text{ V}$ $I_D = 22\text{ A}$ $V_{GS} = 10\text{ V}$                                                       |      | 26<br>8<br>9 | 40        | nC<br>nC<br>nC |

**SWITCHING OFF**

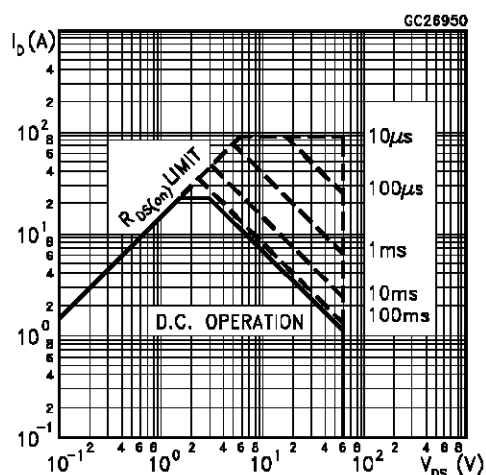
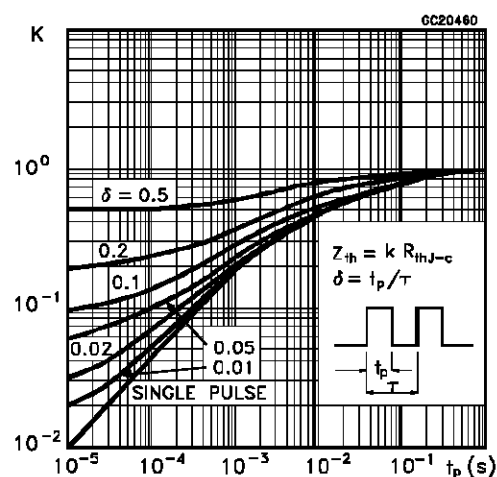
| Symbol                          | Parameter                                             | Test Conditions                                                                                                         | Min. | Typ.            | Max.              | Unit           |
|---------------------------------|-------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------|------|-----------------|-------------------|----------------|
| $t_{r(Voff)}$<br>$t_f$<br>$t_c$ | Off-voltage Rise Time<br>Fall Time<br>Cross-over Time | $V_{DD} = 40\text{ V}$ $I_D = 22\text{ A}$<br>$R_G = 50\ \Omega$ $V_{GS} = 10\text{ V}$<br>(see test circuit, figure 5) |      | 80<br>80<br>170 | 120<br>120<br>250 | ns<br>ns<br>ns |

**SOURCE DRAIN DIODE**

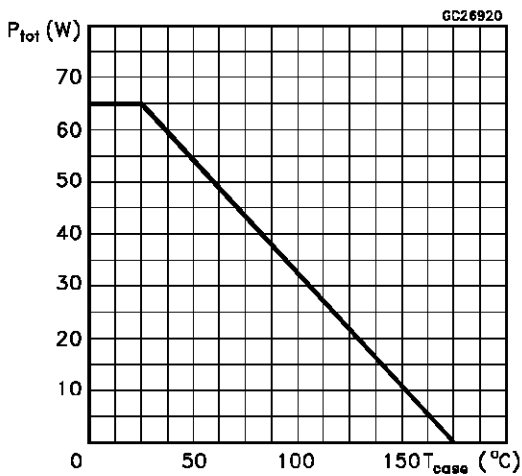
| Symbol                            | Parameter                                                                             | Test Conditions                                                                                                                                       | Min. | Typ.              | Max.     | Unit                     |
|-----------------------------------|---------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------|------|-------------------|----------|--------------------------|
| $I_{SD}$<br>$I_{SDM}(\bullet)$    | Source-drain Current<br>Source-drain Current<br>(pulsed)                              |                                                                                                                                                       |      |                   | 22<br>88 | A<br>A                   |
| $V_{SD} (*)$                      | Forward On Voltage                                                                    | $I_{SD} = 22\text{ A}$ $V_{GS} = 0$                                                                                                                   |      |                   | 1.5      | V                        |
| $t_{rr}$<br>$Q_{rr}$<br>$I_{RRM}$ | Reverse Recovery<br>Time<br>Reverse Recovery<br>Charge<br>Reverse Recovery<br>Current | $I_{SD} = 22\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$<br>$V_{DD} = 30\text{ V}$ $T_j = 150\text{ }^\circ\text{C}$<br>(see test circuit, figure 5) |      | 80<br>0.22<br>5.5 |          | ns<br>$\mu\text{C}$<br>A |

(\*) Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %

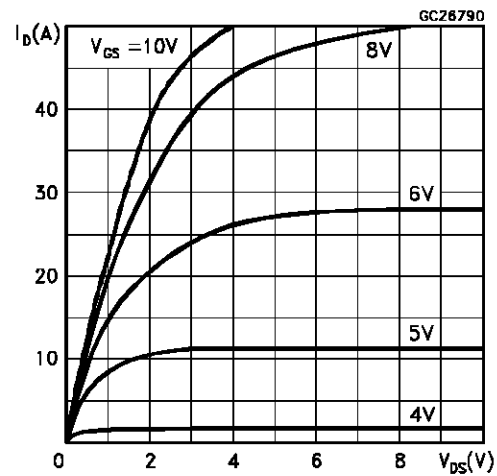
(•) Pulse width limited by safe operating area

**Safe Operating Area****Thermal Impedance**

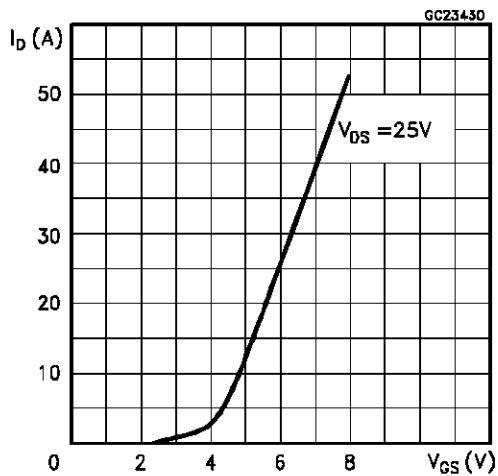
Derating Curve



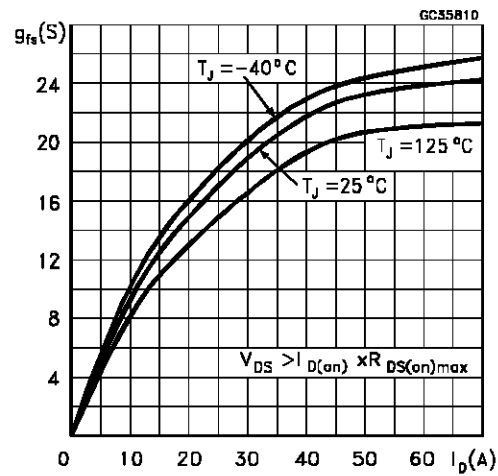
Output Characteristics



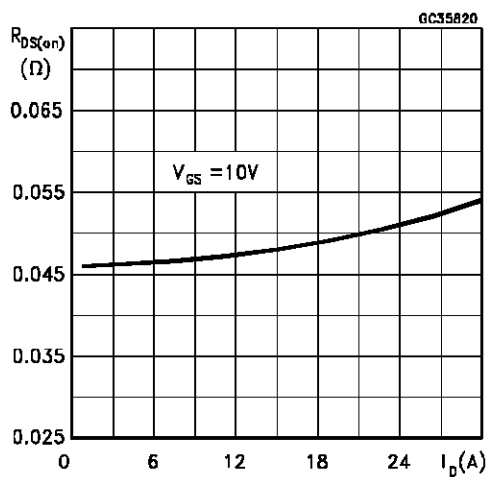
Transfer Characteristics



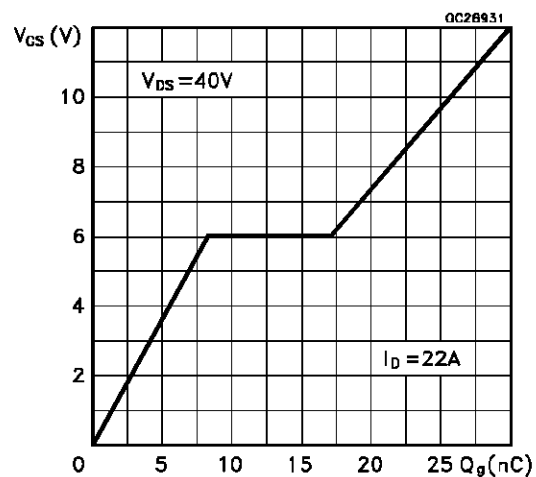
Transconductance



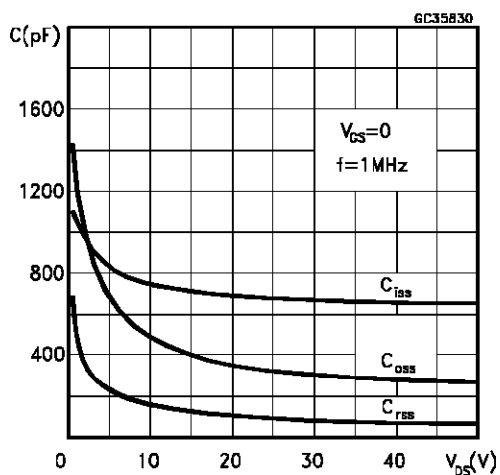
Static Drain-source On Resistance



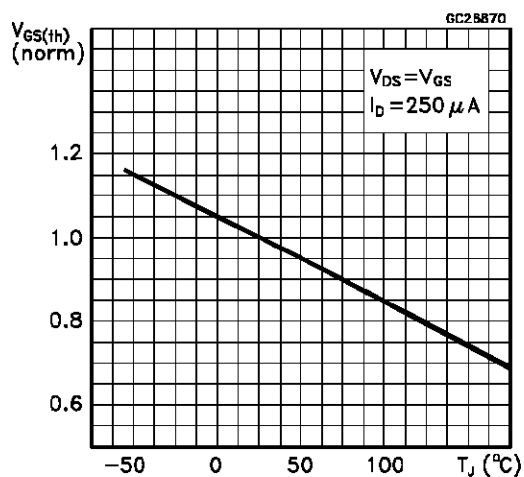
Gate Charge vs Gate-source Voltage



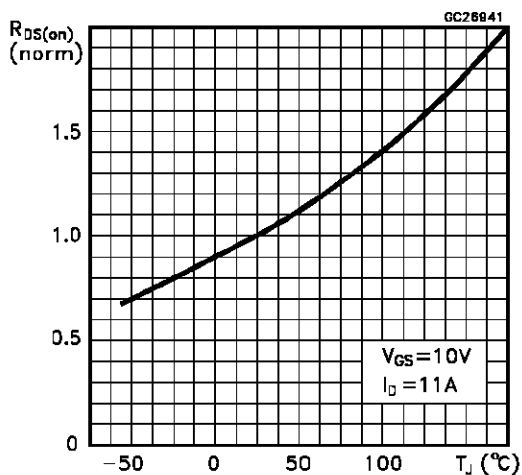
Capacitance Variations



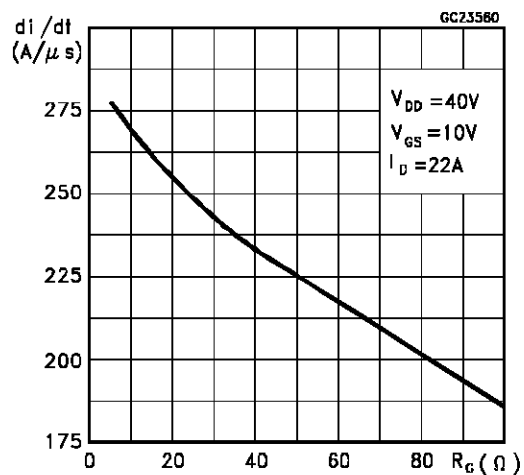
Normalized Gate Threshold Voltage vs Temperature



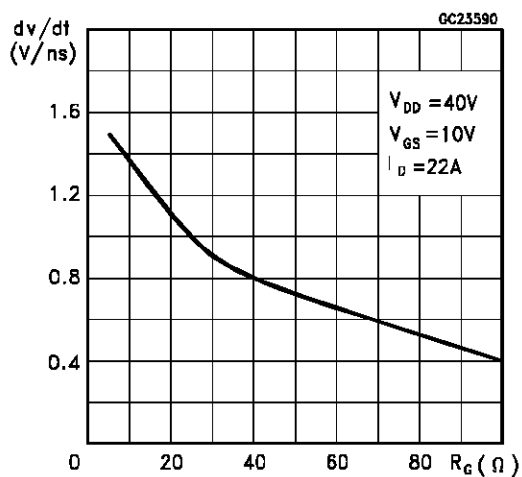
Normalized On Resistance vs Temperature



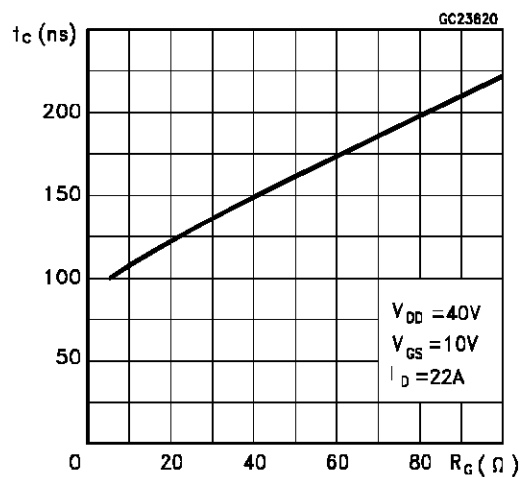
Turn-on Current Slope



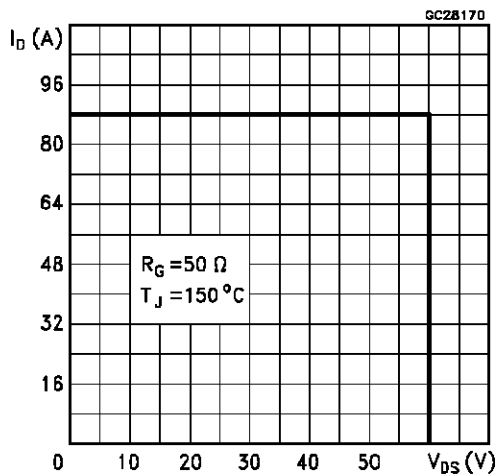
Turn-off Drain-source Voltage Slope



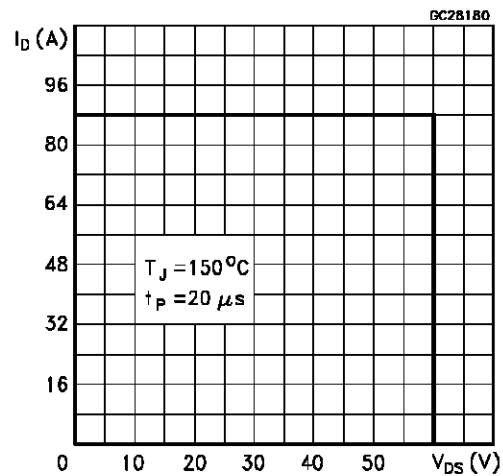
Cross-over Time



Switching Safe Operating Area



Accidental Overload Area



Source-drain Diode Forward Characteristics

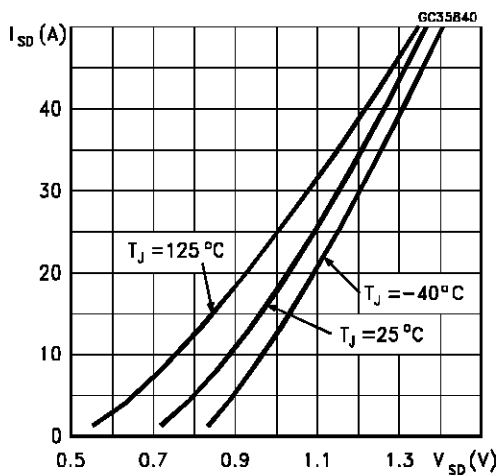
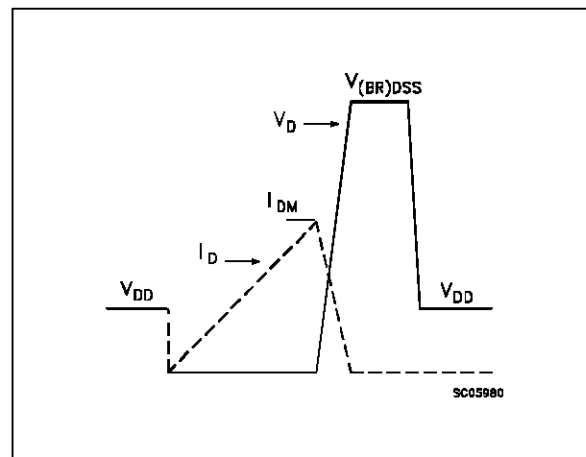
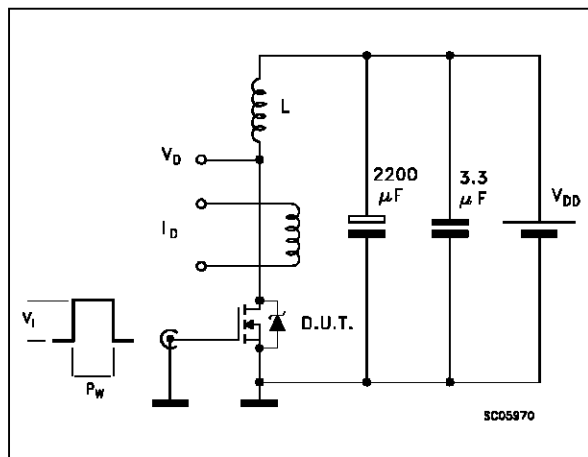
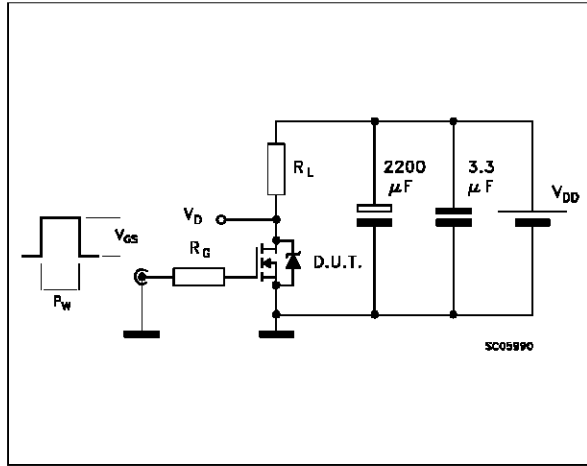


Fig. 1: Unclamped Inductive Load Test Circuits

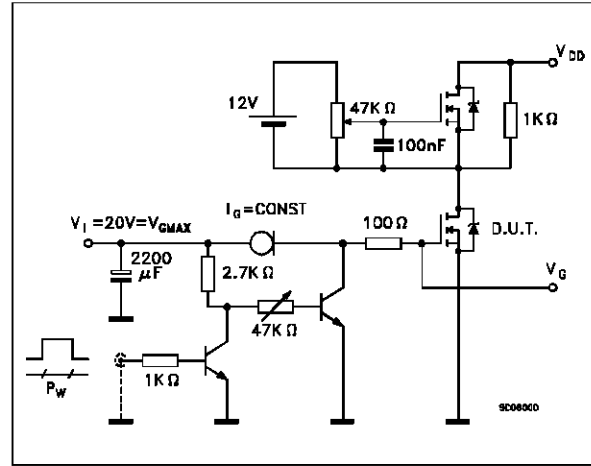
Fig. 2: Unclamped Inductive Waveforms



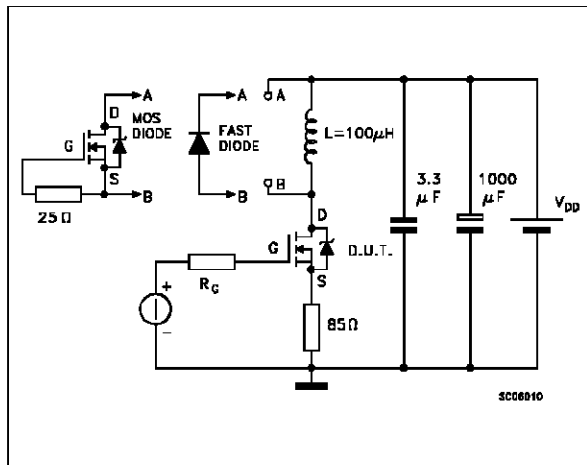
**Fig. 3:** Switching Times Test Circuits For Resistive Load



**Fig. 4:** Gate Charge Test Circuit

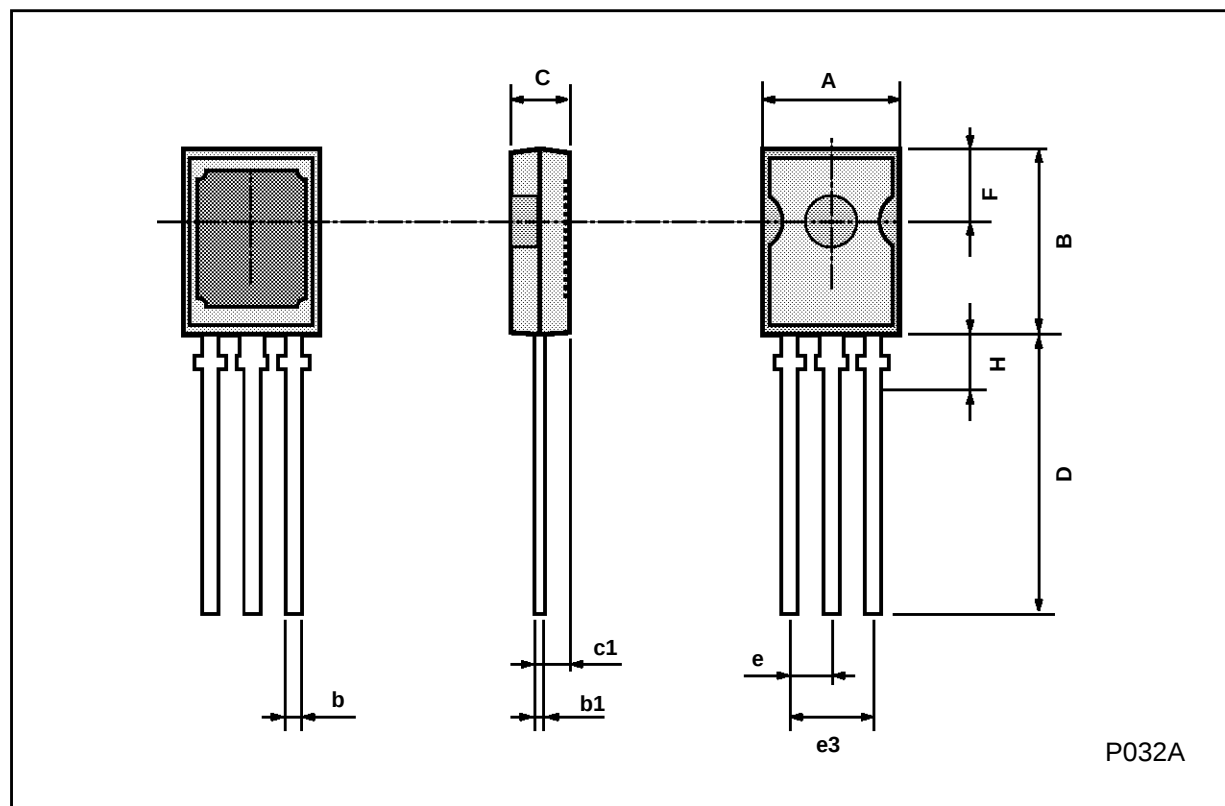


**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Recovery Times



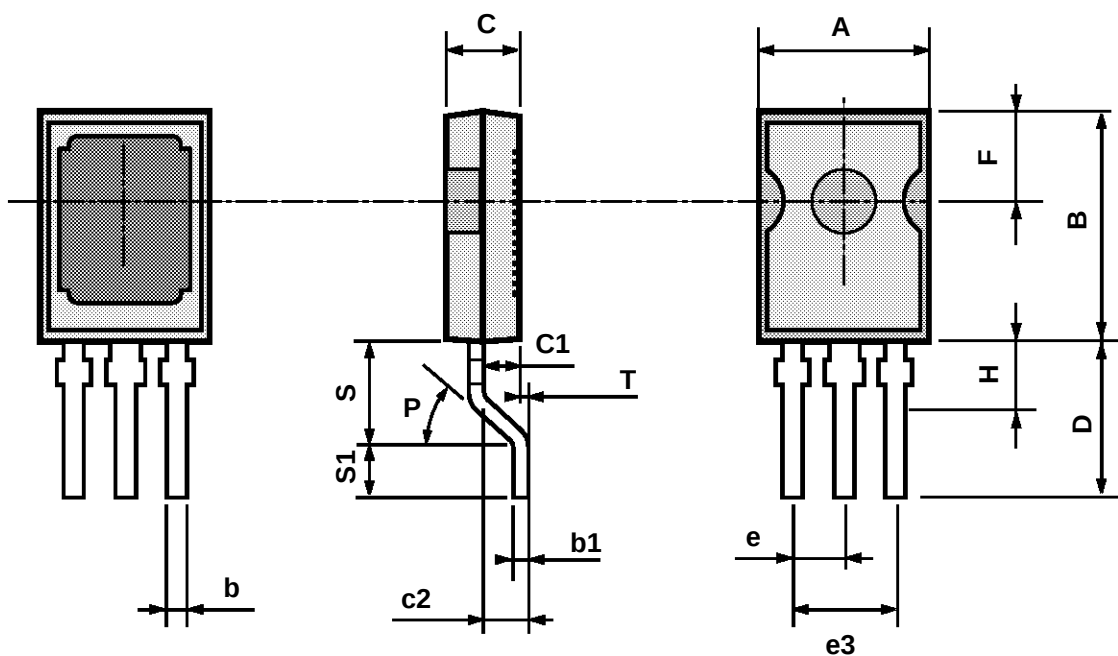
## SOT-82 MECHANICAL DATA

| DIM. | mm   |      |      | inch  |       |       |
|------|------|------|------|-------|-------|-------|
|      | MIN. | TYP. | MAX. | MIN.  | TYP.  | MAX.  |
| A    | 7.4  |      | 7.8  | 0.291 |       | 0.307 |
| B    | 10.5 |      | 11.3 | 0.413 |       | 0.445 |
| b    | 0.7  |      | 0.9  | 0.028 |       | 0.035 |
| b1   | 0.49 |      | 0.75 | 0.019 |       | 0.030 |
| C    | 2.4  |      | 2.7  | 0.04  |       | 0.106 |
| c1   |      | 1.2  |      |       | 0.047 |       |
| D    |      | 15.7 |      |       | 0.618 |       |
| e    |      | 2.2  |      |       | 0.087 |       |
| e3   |      | 4.4  |      |       | 0.173 |       |
| F    |      | 3.8  |      |       | 0.150 |       |
| H    |      |      | 2.54 |       | 0.100 |       |



## SOT-194 MECHANICAL DATA

| DIM. | mm         |      |      | inch  |       |       |
|------|------------|------|------|-------|-------|-------|
|      | MIN.       | TYP. | MAX. | MIN.  | TYP.  | MAX.  |
| A    | 7.4        |      | 7.8  | 0.291 |       | 0.307 |
| B    | 10.5       |      | 11.3 | 0.413 |       | 0.445 |
| b    | 0.7        |      | 0.9  | 0.028 |       | 0.035 |
| b1   | 0.49       |      | 0.75 | 0.019 |       | 0.030 |
| C    | 2.4        |      | 2.7  | 0.094 |       | 0.106 |
| c1   |            | 1.2  |      |       | 0.047 |       |
| c2   |            | 1.3  |      |       | 0.051 |       |
| D    |            | 6    |      |       | 0.236 |       |
| e    |            | 2.2  |      |       | 0.087 |       |
| e3   |            | 4.4  |      |       | 0.173 |       |
| F    |            | 3.8  |      |       | 0.150 |       |
| H    |            |      | 2.54 |       |       | 0.100 |
| P    | 45° (typ.) |      |      |       |       |       |
| S    |            | 4    |      |       | 0.157 |       |
| S1   |            | 2    |      |       | 0.079 |       |
| T    |            | 0.1  |      |       | 0.004 |       |



P032B

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